CnC Tech
Industrial Cable and Connector Technology

CnC Tech Soldering Recommendations for the 3X10, 3X20, and 3221 Series

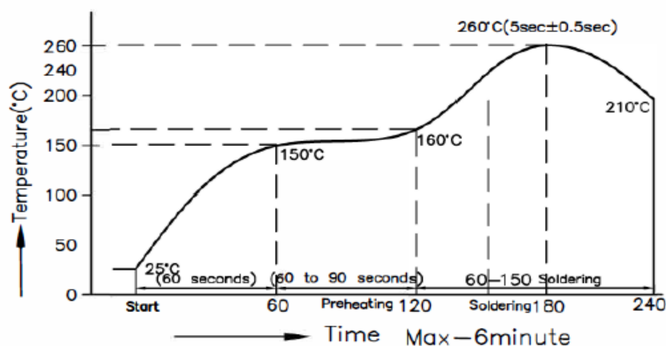
Recommended temperature and time periods for the soldering process

Series	Soldering Method	Temperature in the furnace (lead-free)	Plastic	Furnace time	Soldering time
3020-XX-0100-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3020-XX-0200-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3020-XX-0300-00	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3020-XX-0300-00-TR	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3220-XX-0100-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3220-XX-0200-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3220-XX-0300-00	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3220-XX-0300-00-TR	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3221-XX-0100-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3221-XX-0200-00	wave	235°C ± 5°C	9T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3221-XX-0300-00	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3221-XX-0300-00-TR	reflow	260°C ± 5°C	9T	4~6 mins.	5±0.5 sec
3010-XX-001-12-00	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
3010-XX-001-13-00	wave	235°C ± 5°C	PBT	4~6 mins.	5±0.5 sec
3010-XX-003-12-00	reflow	260°C ± 5°C	6T	4~6 mins.	5±0.5 sec
3010-XX-003-13-00	reflow	260°C ± 5°C	6T	4~6 mins.	5±0.5 sec
3210-XX-001-12-00	wave	235°C ± 5°C	6T	4~6 mins.	5±0.5 sec
	reflow	260°C ± 5°C	6T	4~6 mins.	5±0.5 sec
3210-XX-003-12-00	reflow	260°C ± 5°C	6T	4~6 mins.	5±0.5 sec

Reflow Soldering

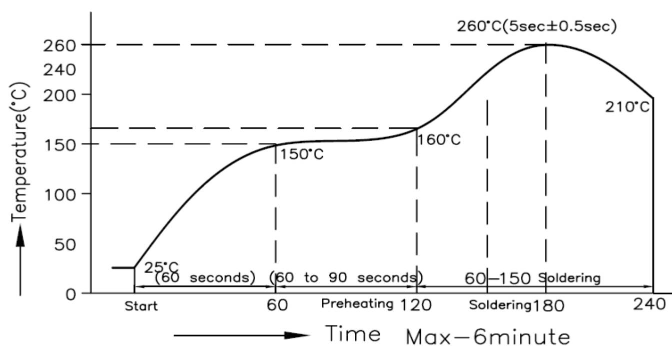
Solderbility Profile

Sub=Nylon 6T Material Temperature Specification   Date:Jun-20-2011 REV:E

Solder regular Condition	1)Soldering temp:260°C±5°C 2)Time:5±0.5 sec 3)Solder wetting percentage:95% min
Reflow Condition	Test Conditions
 Nylon 6T Recommended Temperature Profile	1)Solder Method: Reflow or Wave -Soldering 2)Environment: Room air 3)Solder Composition: Soldering Paste 4)Test Board: 52mmX36.5mmX1.6mm thick 5) This temperature profile is based on the above conditions. Individual applications the actual temperature may vary.Consult your solder paste and equipment manufacturer for specific recommendations 6)There must not be visible defect after testing

Solderbility Profile

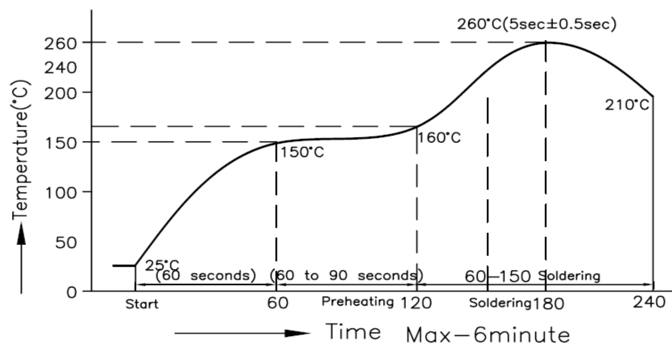
Sub=Nylon 9T Material Temperature Specification   Date:Jun-20-2011 REV:E

Solder regular Condition	1)Soldering temp:260°C±5°C 2)Time:5±0.5 sec 3)Solder wetting percentage:95% min
Reflow Condition	Test Conditions
 Nylon 9T Recommended Temperature Profile	1)Solder Method: Reflow or Wave 2)Environment: Room air 3)Solder Composition: Soldering Paste 4)Test Board: 52mmX36.5mmX1.6mm thick 5) This temperature profile is based on the above conditions. Individual applications the actual temperature may vary.Consult your solder paste and equipment manufacturer for specific recommendations 6)There must not be visible defect after testing

Reflow Soldering

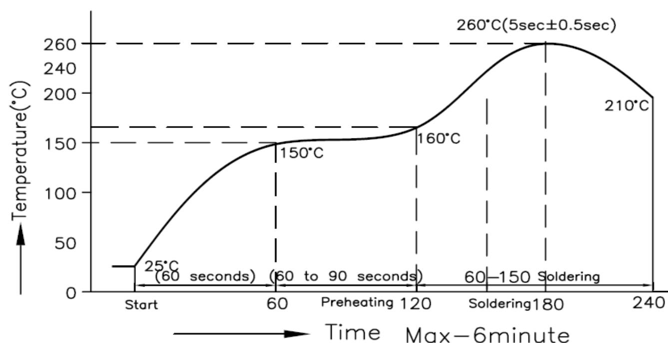
Solderbility Profile

Sub=Nylon 46 Material Temperature Specification   Date:Jun-20-2011 REV:E

Solder regular Condition	1)Soldering temp:260°C±5°C 2)Time:5±0.5 sec 3)Solder wetting percentage:95% min
Reflow Condition	Test Conditions
 Nylon 46 Recommended Temperature Profile	1)Solder Method: Reflow or Wave 2)Environment: Room air 3)Solder Composition: Soldering Paste 4)Test Board: 52mmX36.5mmX1.6mm thick 5) This temperature profile is based on the above conditions. Individual applications the actual temperature may vary.Consult your solder paste and equipment manufacturer for specific recommendations 6)There must not be visible defect after testing

Solderbility Profile

Sub=LCP Material Temperature Specification   Date:Jun-20-2011 REV:E

Solder regular Condition	1)Soldering temp:260°C±5°C 2)Time:5±0.5 sec 3)Solder wetting percentage:95% min
Reflow Condition	Test Conditions
 LCP Recommended Temperature Profile	1)Solder Method: Reflow or Wave 2)Environment: Room air 3)Solder Composition: Soldering Paste 4)Test Board: 52mmX36.5mmX1.6mm thick 5) This temperature profile is based on the above conditions. Individual applications the actual temperature may vary.Consult your solder paste and equipment manufacturer for specific recommendations 6)There must not be visible defect after testing

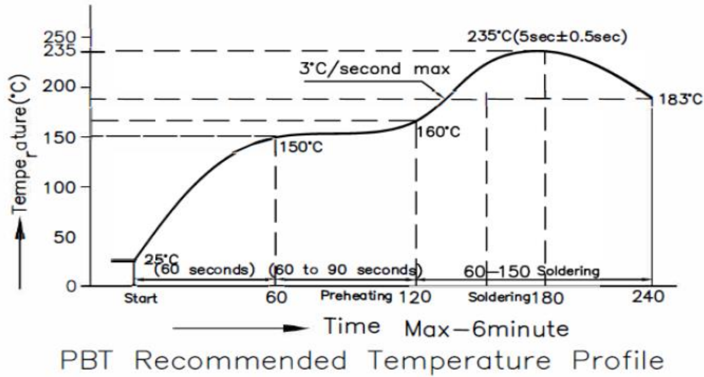
Wave Soldering

Solderbility Profile

Sub=PBT Material Temperature Specification

Date:Jun-20-2011 REV:E

Solder regular Condition	1)Soldering temp:235°C±5°C 2)Time:5±0.5 sec 3)Solder wetting percentage:95% min
Wave Condition	Test Conditions



PBT Recommended Temperature Profile

1)Solder Method:Wave -Soldering
2)Environment: Room air
3)Solder Composition: Soldering Paste
4)Test Board: 52mmX36.5mmX1.6mm thick
5) This temperature profile is based on the above conditions. Individual applications the actual temperature may vary.Consult your solder paste and equipment manufacturer for specific recommendations
6)There must not be visible defect after testing